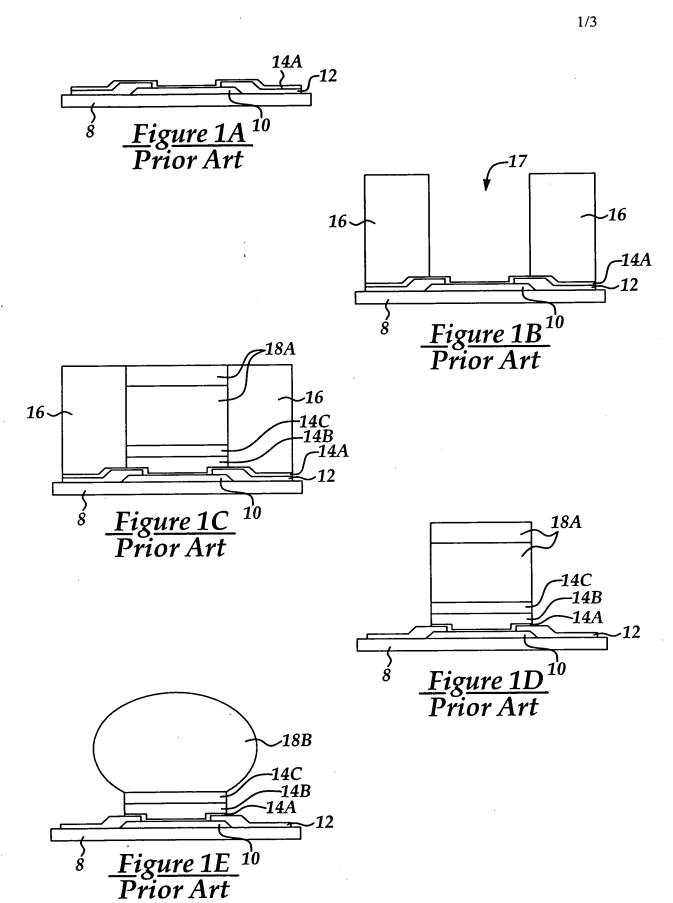
Inventor(s): Su, et al Serial No.: To Be Assigned Filed: Herewith

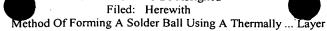
r: Method Of Forming A Solder Ball Using A Thermally ... Layer

Attorney Docket No.: 67,200-630



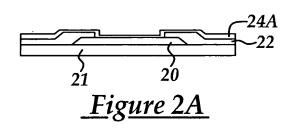
Inventor(s): Su, et al Serial No.: To Be Assigned

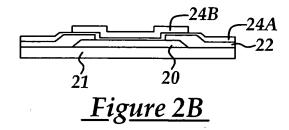
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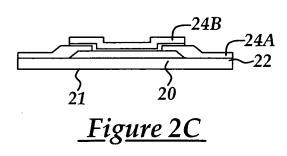


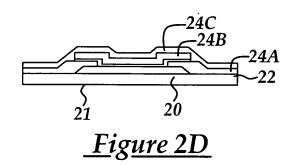
Attorney Docket No.: 67,200-630

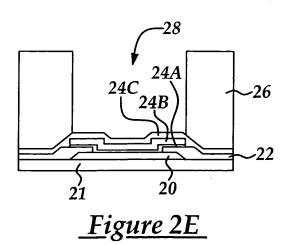
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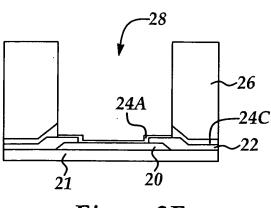
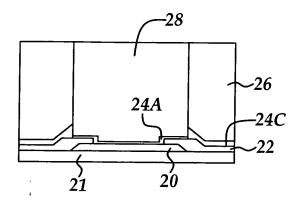


Figure 2F

Inventor(s): Su, et al
Serial No.: To Be Assigned
Filed: Herewith

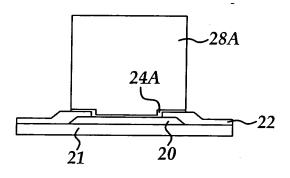
For: Method Of Forming A Solder Ball Using A Thermally ... Layer

Attorney Docket No.: 67,200-630

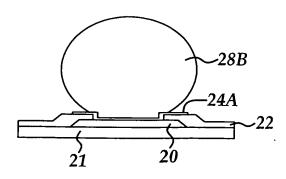


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<u>Figure 3A</u>



<u>Figure 3B</u>



<u>Figure 3C</u>